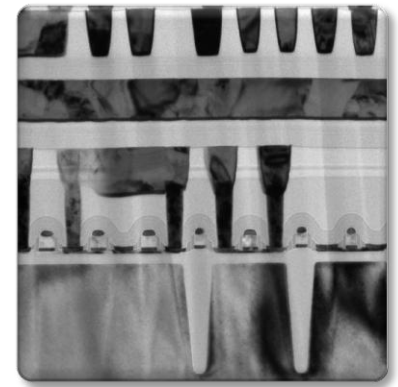
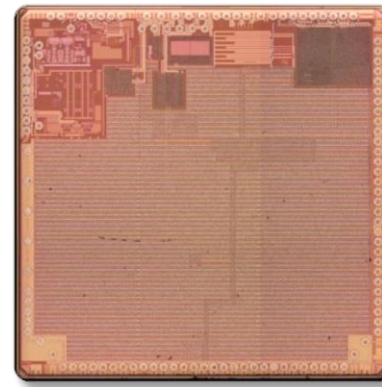
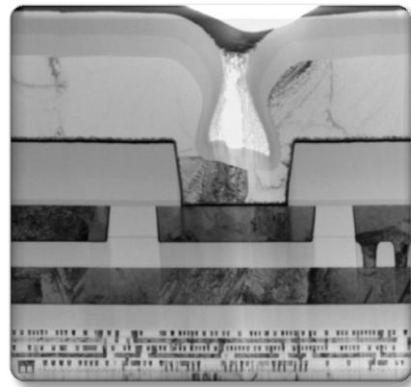


# CXD5603

GNSS Receiver ( Fully-Depleted Silicon-On-Insulator )



## Product Analysis Report

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To Know



- Device Summary.....3
  - Device Summary
- Package Overview .....4
  - Package Overview
  - X-Ray Overview
- Die Photo.....6
  - Die Photo with Dimensions
- Die Corner.....7
  - Die Corner OM Image
- Die Pad Size.....8
  - PAD Size with Dimensions
- Die Cross Section TEM Analysis.....9
  - Die Cross Section TEM Image, General Structure
  - Die Cross Section TEM Image, Passivation to Metal 8
  - Die Cross Section TEM Image, Barrier Metal of Metal 8
  - Die Cross Section TEM Image, IMD 7 to Metal 7
  - Die Cross Section TEM Image, IMD 6 to Metal 6
  - Die Cross Section TEM Image, IMD 5

- Die Cross Section TEM Image, Metal 5 to Metal 1
- Die Cross Section TEM Image, Metal 5 to IMD3
- Die Cross Section TEM Image, Metal 3 to IMD2
- Die Cross Section TEM Image, Metal 2 to IMD1
- Die Cross Section TEM Image, STI Measurements
- Die Cross Section TEM Image, Metal 1 to PMD
- Die Cross Section TEM Image, Gate Pitch Measurement
- Die Cross Section TEM Image, Gate Spacer Measurement
- Die Cross Section TEM Image, Gate Cap Measurement
- Die Cross Section TEM Image, Gate Lattice Measurement
- Die Cross Section TEM Image, Gate Oxide Measurement
- Die Cross Section TEM Image, Oxide of SOI Measurement
- Die Cross Section TEM EDX Analysis.....30
  - Cross Section TEM EDX Line Scan Analysis, MOS Area
  - Cross Section TEM EDX Line Scan Analysis, Gate Oxide Area
- Major Findings .....32
  - Summary